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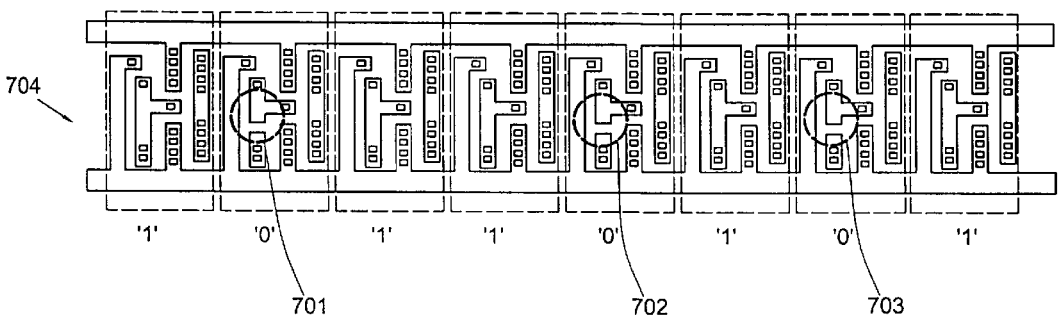
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(54) Title: PERSONALIZED HARDWARE



(57) Abstract: A system for personalizing one or more electrical circuits having plurality of layers with electrical characteristics. The layers being produced by an electrical characteristic determination process (ECDP). The system for personalizing includes a wafer stage for receiving a wafer in order to produce a plurality of electrical circuits. The system is configured to apply a personalization process during production of the layers. The personalization process includes using a first ECDP in the layer to produce identical electrical characteristics on the wafer in each of the plurality of electrical circuits, and using a second ECDP in the layer to modify one or more electrical characteristics in selected electrical circuits so as to incorporate in the selected circuits an individualized digital number, giving rise to the desired personalizing of one or more of the specified electrical circuits. Related apparatus and methods are also provided.

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